

DIM X±0.2 ON TIP-

— DIMY —

spec ref	*			dr	Andrew Yong		2010/10/21	proje	ction
tolerance std	T 0 1 F 1			eng	Roger Ng		2014/04/07		
ISO 406	TOLERANCES UNLESS OTHERWISE SPECIFIED			chr	-		-	Ψ	
ISO 0				appr	Rick Bian		2014/04/17	product	family
		0.X	±-	ſ		● M I	NITEK II		
surface /	linear	0.XX	±0.25		Çj	— V +			
\vee		0.XXX	± -]	Y		(HTP)		
ISO I302	angular	0°	±-°	www	.fci.com	cat.no).		
2						3	PDS: Rev	:Н	
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0.1 NON ACCUM

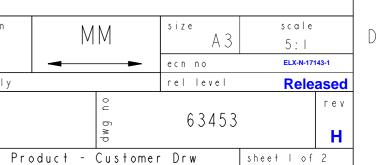
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→ 2.0 →

◄ 4.2 -----

<u>TO 1.3</u> Hole layout



STATUS:Released

Printed: Apr 17, 2014

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	PRODUCT NO	PRODUCT NO	POS	DIM X	DIM Y
	63453-X04	63453-X04LF (8)	2 X 2	2	4.8
	X 0 6	XO6LF A	2 X 3	4	6.8
	X 0 8	X08LF	2 X 4	6	8.8
А	ХІО	XIOLF	2 X 5	8	10.8
	X I 2	XI2LF	2 X 6	10	12.8
	X 4	XI4LF	2 X 7	12	4.8
	X I 6	XI6LF	2 X 8	4	16.8
	X I 8	XI8LF	2 X 9	16	18.8
B	X 2 0	X20LF	2 X I O	18	20.8
	X 2 2	X22LF	2 X I I	20	22.8
	X 2 4	X24LF	2 X I 2	22	24.8
	X 2 6	X26LF	2 X I 3	2 4	26.8
	X 2 8	X28LF	2 X 4	26	28.8
	X 3 0	X 30 L F	2XI5	28	30.8
	X 3 2	X32LF	2 X I 6	30	32.8
	X 3 4	X34LF	2 X I 7	32	34.8
	Х36	X36LF	2 X I 8	34	36.8
	X 3 8	X38LF	2XI9	36	38.8
	X 4 0	X40LF	2 X 2 0	38	40.8
	X 4 2	X42LF	2 X 2 I	40	42.8
	X 4 4	X 4 4 L F	2 X 2 2	42	44.8
	X 4 6	X46LF	2 X 2 3	44	46.8
	X 4 8	X48LF 🔻	2 X 2 4	46	48.8
С	X 5 0	X 50 L F (8)	2 X 2 5	48	50.8

PART NUMBER INFORMATION

XXXXX-XXXLF LEAD FREE — TERMINAL PLATING -BASE P/N

NOTES:

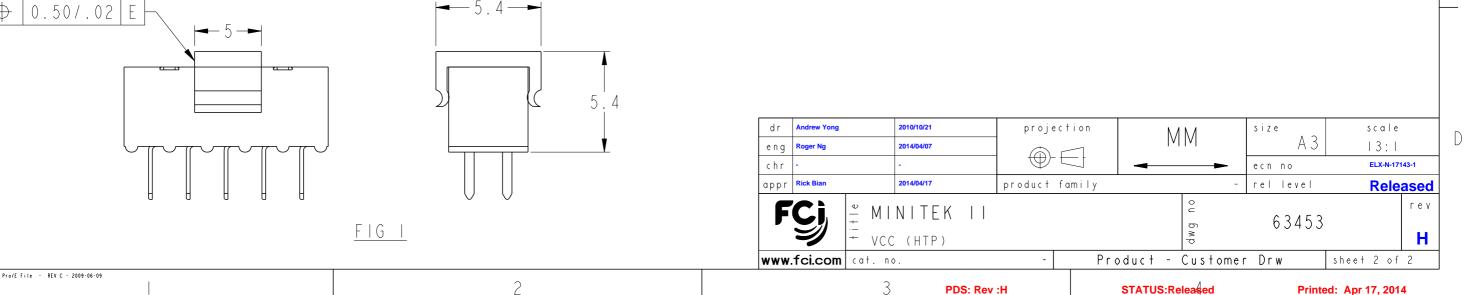
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I.MATERIAL :

BODY : GLASS FILLED PCT UL 94V-O BLACK TERMINAL : PHOSPHOR BRONZE

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- 2. CUT SURFACE IS UNPLATED
- 3. TERMINAL RETENTION FORCE 0.5 Kg MIN
- 4. TOLERANCE UNLESS OTHERWISE NOTED ± 0.25
- 5. 63453-XXX PACKAGING IN TUBE WITHOUT PLASTIC CAP. 63453-XXXTR PACKAGING IN TAPE AND REEL WITH PLASTIC CAP. 63453-XXXTRN PACKAGING IN TAPE AND REEL WITHOUT PLASTIC CAP. A PICK-UP CAP IS PROVIDED IN THE CENTRE OF THE PRODUCT (SEE FIG.I) FOR PICK AND PLACE APPLICATION.
- 6. THE HOUSING WILL WITHSTAND EXPOSURE TO 255° C PEAK TEMPERATURE FOR IO SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.
- 7. THE HOUSING WILL WITHSTAND EXPOSURE TO 260°C PEAK TEMPERATURE FOR IO SECONDS IN A WAVE SOLDER APPLICATION WITH A 1.57MM MINIMUM THICK CIRCUT BOARD.
- 8. THIS PRODUCT MEETS EUROPEAN UNION DIRECTIVES AND OTHER COUNTRY REGULATIONS AS DESCRIBED IN GS-22-008.



PICK-UP CAP

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PLATING	DESCRIPTION (CONTACT AREA)	
0	0.2 µm Au	
	0.76 µm Au	
2	UNASSIGNED	
3	0.38 µm Au	
4	2.54 µm Matte Tin	

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С

Mouser Electronics

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